TITLE OF INVENTION:

SUBSTRATE POLISHING DEVICE

ABSTRACT

A substrate polishing device is provided. The substrate polishing device includes a polishing table, a top ring, a polishing surface cleaning part, a substrate cleaning part and a control part. The polishing table has a polishing surface for performing a substrate polishing on a substrate. The top ring moves freely between a polishing position and a handover position, and holds the substrate and presses it against the polishing surface. The polishing surface cleaning part is provided corresponding to a cleaning position between the polishing position and the handover position and cleans the polishing surface after the substrate polishing. The control part is configured to clean the substrate by the substrate cleaning part during a cleaning treatment of the polishing surface by the polishing surface cleaning part, and end the cleaning treatment of the polishing surface after the cleaning treatment of the substrate by the substrate cleaning part ends.

FIG. 7